

Metal-clad base materials for printed wiring boards —

**Part 103: Special materials used in
connection with printed circuits —**

**Section 103.2 Specification for copper
foil for use in the manufacture of
copper-clad base materials**

Committees responsible for this British Standard

The preparation of this British Standard was entrusted by the Electronic Components Standards Policy Committee (ECL/-) to Technical Committee ECL/19 upon which the following bodies were represented:

British Telecommunications plc
ERA Technology Ltd.
Electrical and Electronic Insulation Association (BEAMA Ltd.)
Electronic Components Industry Federation
Electronic Engineering Association
GAMBICA (BEAMA Ltd.)
Institute of Circuit Technology
Institute of Metal Finishing
Ministry of Defence
National Supervising Inspectorate
Printed Circuit Association
Telecommunication Engineering and Manufacturing Association

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